ABSTRACT

LASER PROCESSING APPARATUS

A laser processing apparatus includes: a chuck table that holds a packaged wafer; a laser beam applying unit that applies a pulsed laser beam to the packaged wafer; X-axis moving unit for moving the chuck table in an X-axis direction; an imaging unit that images the packaged wafer; and a control unit. The chuck table has a transparent or semi-transparent holding member and a light emitting body. The control unit includes: an imaging instruction section that causes the imaging unit to image the packaged wafer while the pulsed laser beam is being applied to the packaged wafer; and a determination section that determines the processed state of a through-groove from a picked-up image obtained according to an instruction by the imaging instruction section.

(Figure 1)